



**NOTES**

- ▲ 1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN OVER 100 MICRO INCH MIN OF NICKEL PLATED.
- 2. FLATNESS PERTAINS TO METALLIZED PAD ONLY.
- 3. LEAD TO LEAD LEAKAGE MUST NOT EXCEED 5 NANO AMPS AT 100V D.C
- 4. NO PIN CONNECTED TO SEAL AREA AND DIE ATTACH PAD (ZERO GROUND)
- 5. LEAD RESISTANCE : 0.3Ω MAX.
- ▲ 6. PART VARIATION TABLE  
 PART NO VARIATION  
 -01- WITH SEAL METALLIZE  
 -02- NO SEAL METALLIZE

MODIFICATIONS						NAME 24 LEAD CHIP CARRIER	TOLERANCES: UNLESS OTHERWISE SPECIFIED	DRAWN Numanoda	CHECKED S. K.
						SCALE 10/1	±1%	APPROVED	DATE 79-10-12
						MATERIAL KYOCERA A-440	N.L.T ±.005		
	▲ CHANGED : NOTES 1. 6 CHANGE	79-10-26	R. U	D. M.					
	DATE	DRAWN	CHECKED	APPROVED	KYOTO CERAMIC CO., LTD. KYOTO JAPAN		CWG-A	PB-92321-A	